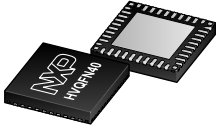


# SOT618-18(DD)

HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

25 July 2023

Package information



## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN40
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	05-10-2022
<b>Manufacturer package code</b>	98ASA01881D

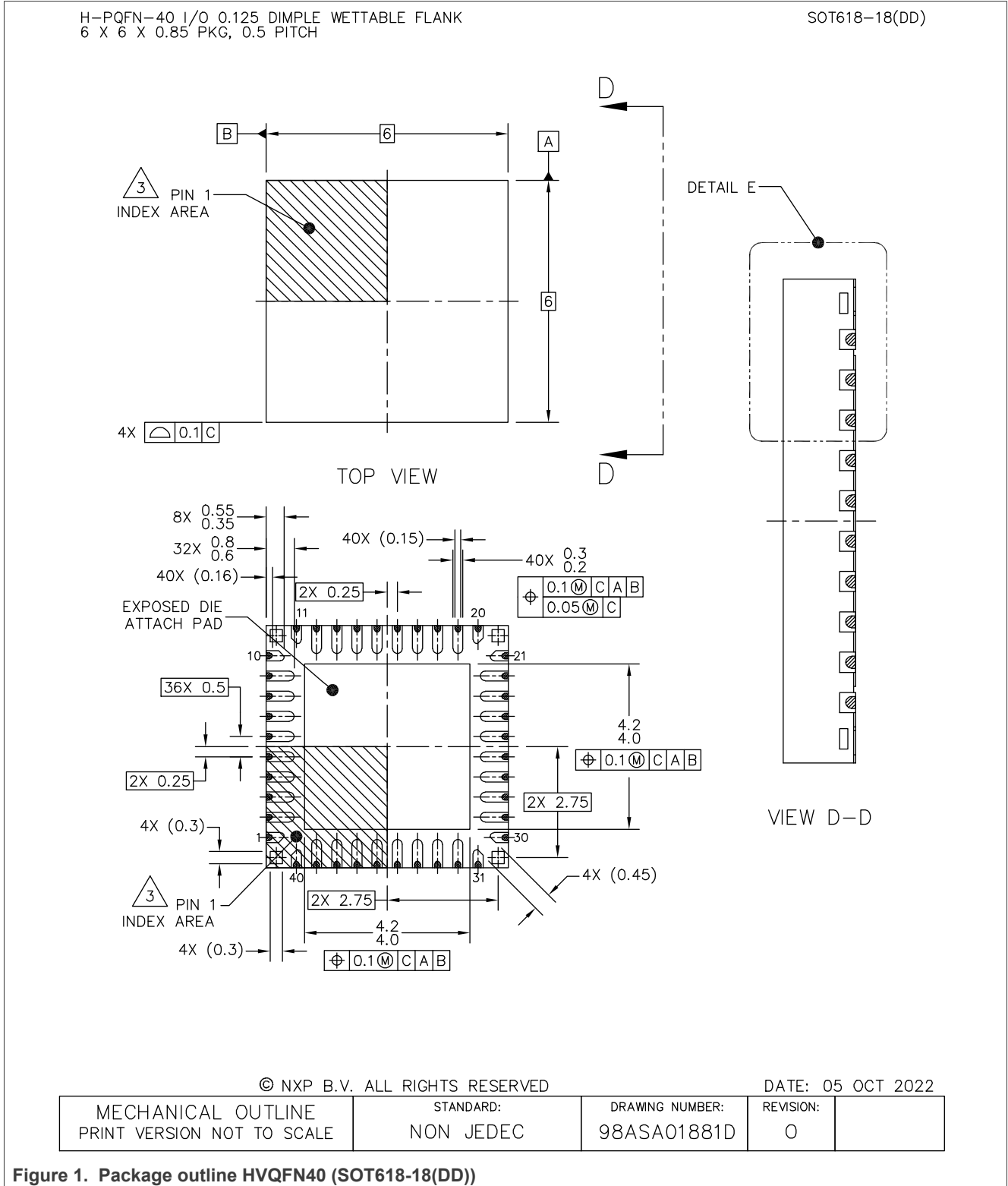
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

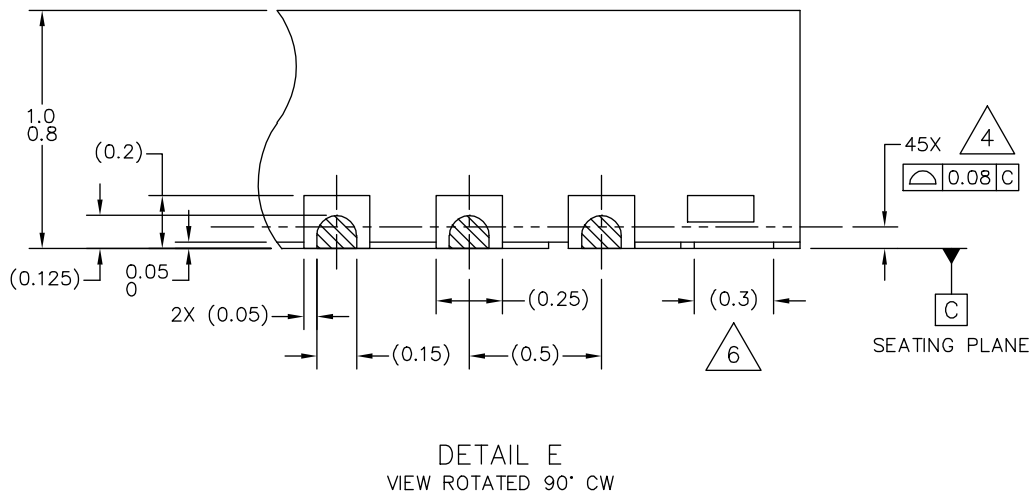
2 Package outline



HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-40 I/O 0.125 DIMPLE WETTABLE FLANK  
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-18(DD)



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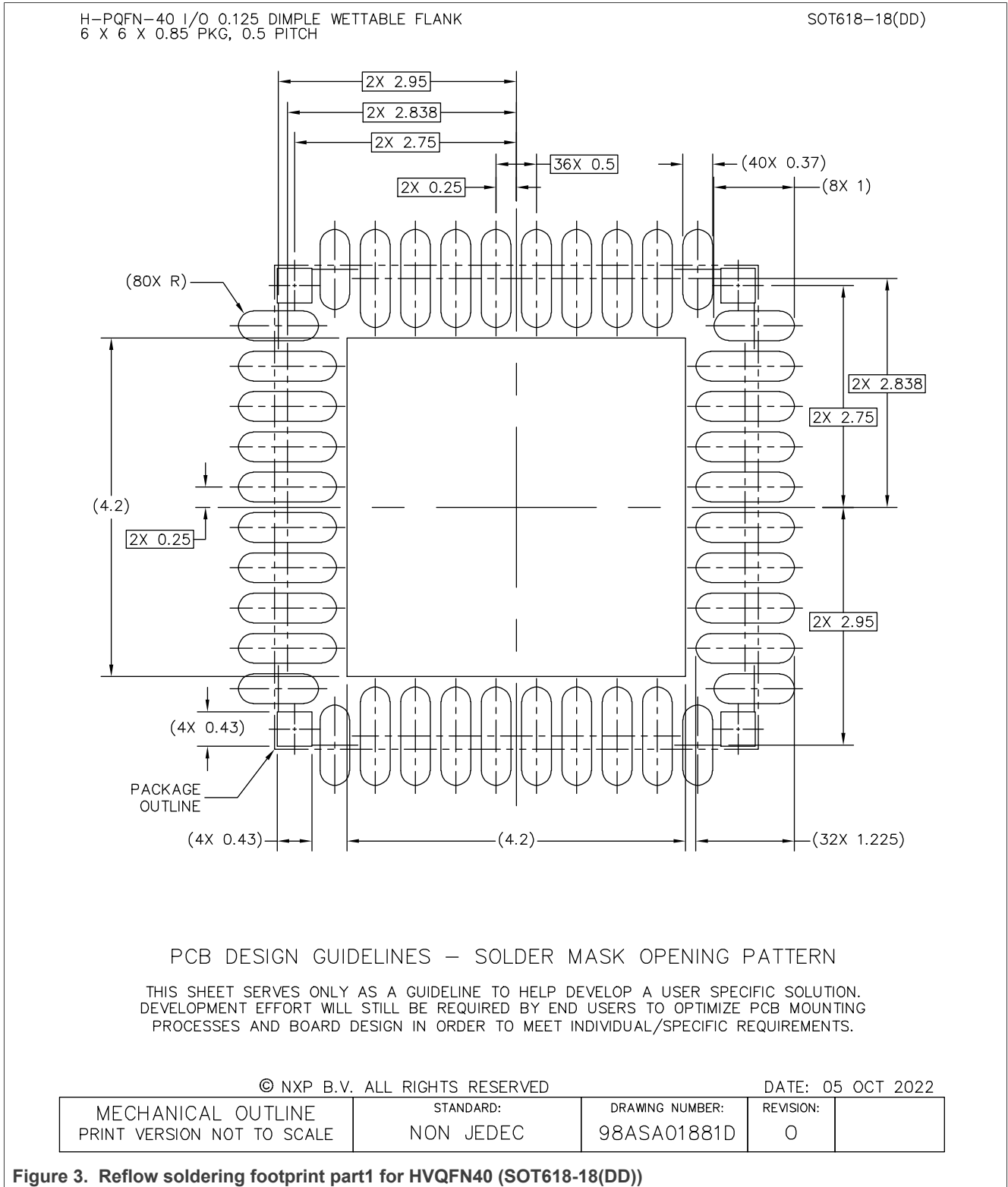
DATE: 05 OCT 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01881D	REVISION: 0	
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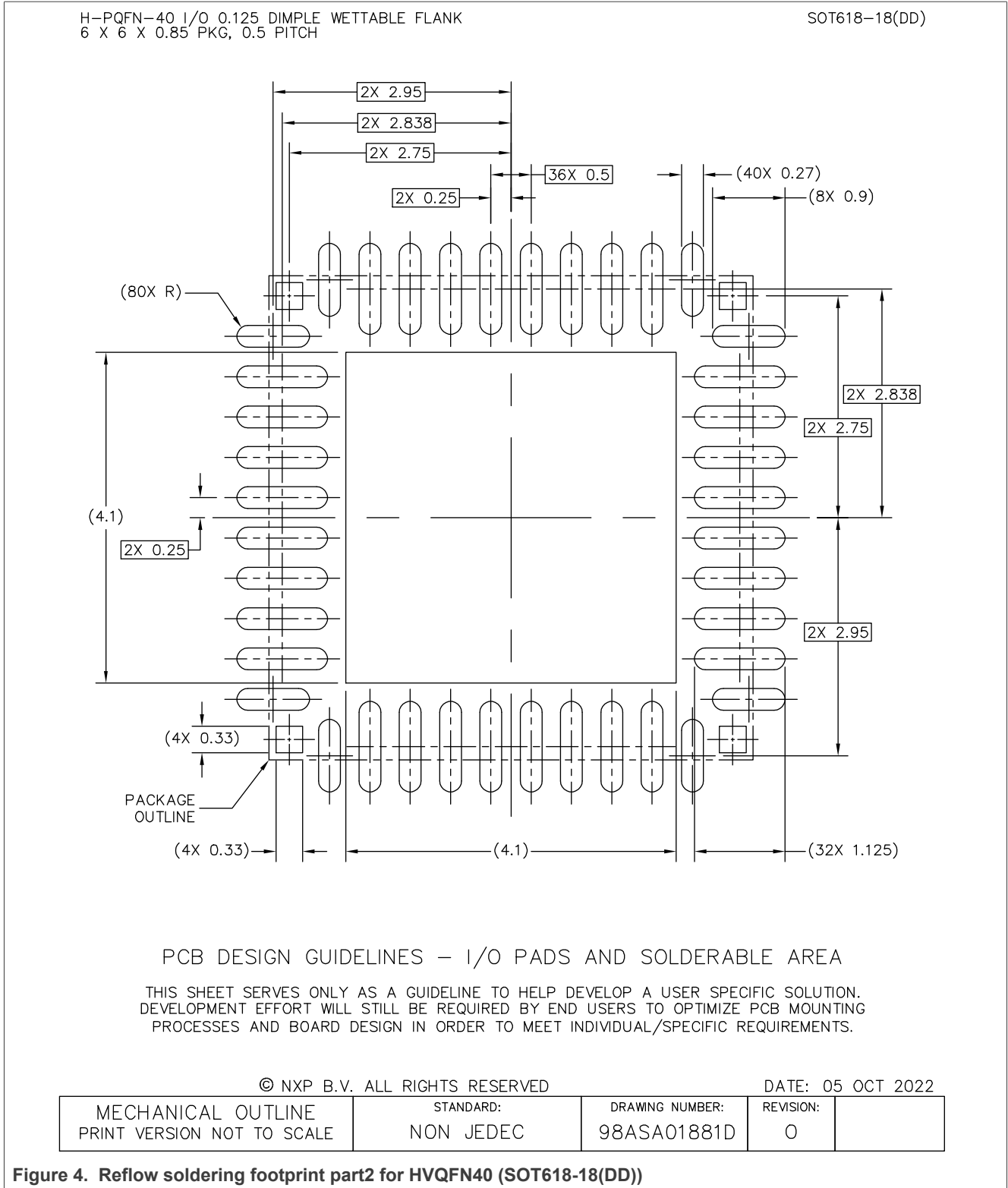
Figure 2. Package outline detail E of HVQFN40 (SOT618-18(DD))

HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

3 Soldering



HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body



HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

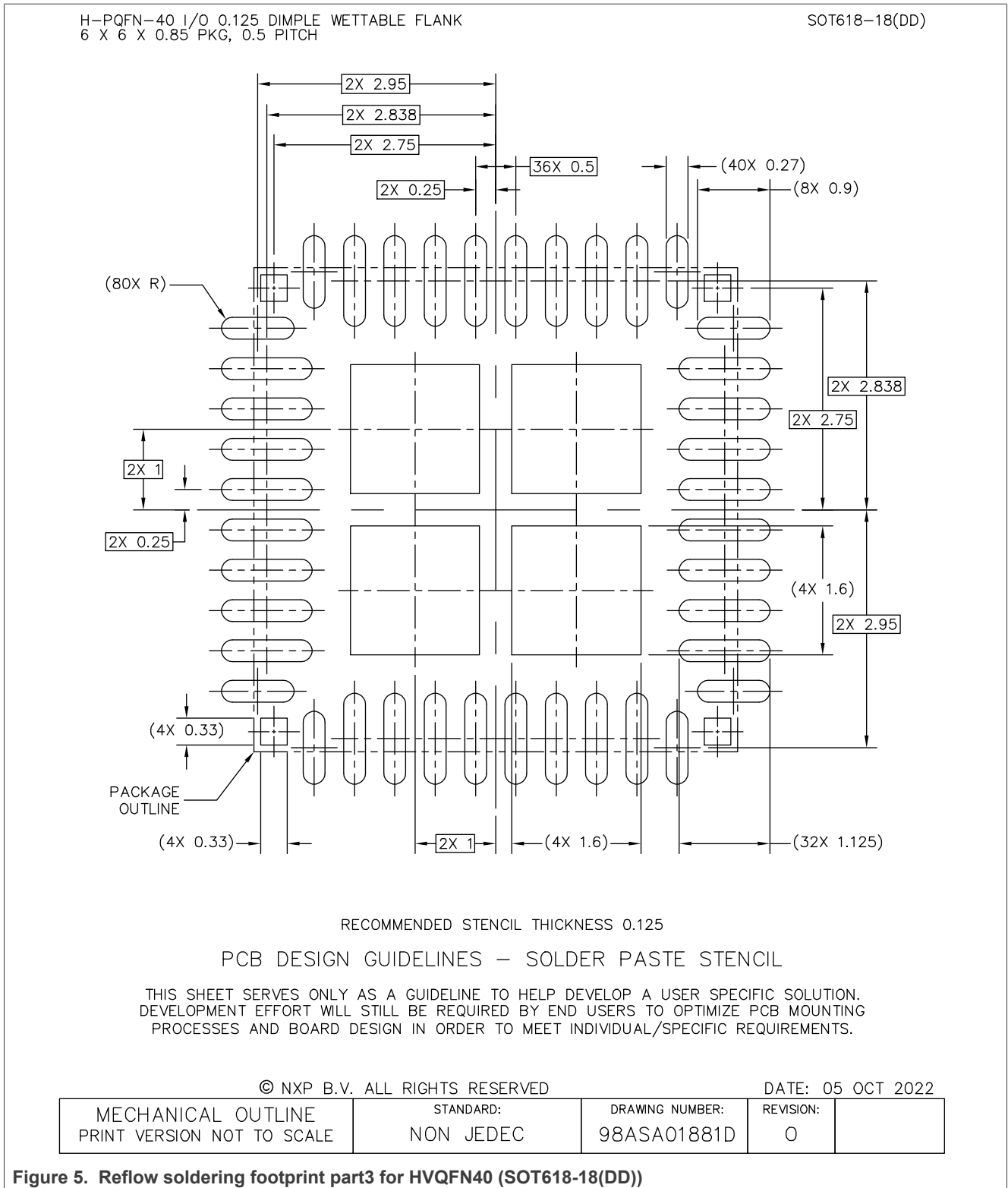


Figure 5. Reflow soldering footprint part3 for HVQFN40 (SOT618-18(DD))

**HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body**

H-PQFN-40 I/O 0.125 DIMPLE WETTABLE FLANK  
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-18(DD)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN40 (SOT618-18(DD))

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HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

## 4 Legal information

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HVQFN40, thermal enhanced very thin quad flat package; no leads; dimple wettable flank; 40 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

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